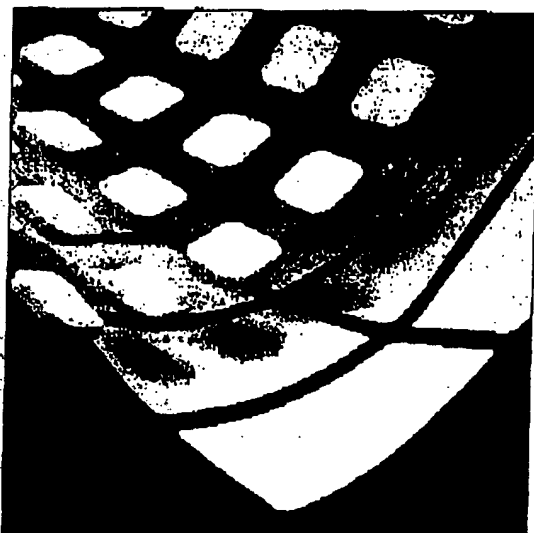


Exhibit A

Advertisements for "thermal interface materials"

1. W.L. Gore and Associates, Inc.'s POLARCHIP™
2. Thermalloy, Inc.'s Thermalcote II
3. Stockwell Rubber Company's Thermal Management Components

Gore's POLARCHIP™ Thermal Interface Materials... Bridge the Gap Between Hot PCBs and Cool Heat Sinks.



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Reader Interest Rating

Please circle the appropriate Reader Inquiry Number in your response form to indicate your level of interest in this article.

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Thermal Management Components To Fill Virtually Any Gap Configuration

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Thermally
Conductive
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